

Document Number: STAV58180L4 Preliminary Datasheet V1.0

STAV58180L4

# GaN HEMT 50V, 180W,5.8GHz RF Power Transistor

### **Description**

The STAV58180L4 is a single ended 180watt, GaN HEMT, ideal for ISM applications at 5.8GHz. It can support CW, pulse and linear applications.

There is no guarantee of performance when this part is used outside of stated frequencies.

Typical pulse CW performance across the band with device soldered

VDD = 50 Vdc,Idq=20mA Tc=25°C, air cooling

Pulsed CW:

Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
5800	52.26	168.2	55.5	14.58	53.54	225.7	58.0

CW:

Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
5800	51.71	148.3	50.0	13.5	53	200	53.0

## **Applications**

- C band Class AB power amplifier
- 5.8GHz RF Energy

### **Important Note: Proper Biasing Sequence for GaN HEMT Transistors**

#### Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

#### Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

### **Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit	
DrainSource Voltage	V <sub>DSS</sub>	+200	Vdc	
GateSource Voltage	V <sub>GS</sub>	-8 to +0.5	Vdc	
Operating Voltage	V <sub>DD</sub>	55	Vdc	
Maximum gate current	Igs	30	mA	
Storage Temperature Range	Tstg	-65 to +150	°C	
Case Operating Temperature	T <sub>C</sub>	+150	°C	
Operating Junction Temperature	TJ	+225	°C	

### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Thermal Resistance, Junction to Case by FEA	Rejc	0.8	°C /W	
T <sub>C</sub> = 25°C, at Pd=180W at 5.8GHz	KAJC	0.8	C/VV	

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Table 3. Electrical Characteristics (TA =  $25^{\circ}$ C unless otherwise noted)

#### **DC Characteristics**

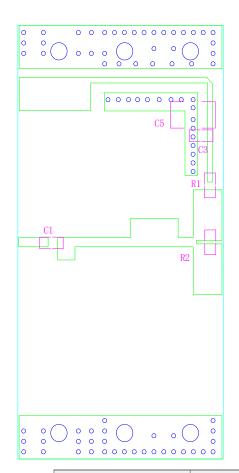
Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=32mA	V <sub>DSS</sub>		200		V
Gate Threshold Voltage	VDS =10V, ID = 32mA	$V_{GS(th)}$	-4	-	-2	V
Gate Quiescent Voltage  VDS =50V, IDS=20mA, Measured in Functional Test		$V_{GS(Q)}$		3.1		V

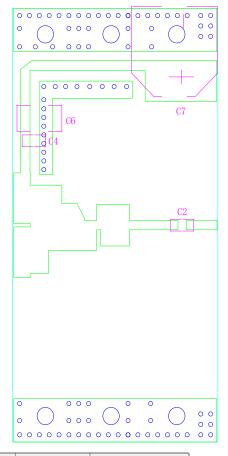
#### **Ruggedness Characteristics**

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	5.8GHz, Pout=180W pulse CW					
	All phase,	VSWR		10:1		
	No device damages					

## **Reference Circuit of Test Fixture Assembly Diagram**

PCB materials: Ro4350B, DXF file upon request





Designator	Comment	Footprint	Quantity
C1, C2, C3, C4	3.9 pF/250V	0805	4
C5, C6	10uF/100V	1210	2
C7	100uF/63V		1
R1, R2	10 Ω	0603	2



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Figure 3: Efficiency and power gain as function of Pout

(VDD = 50 Vdc, IDQ = 100mA, Pulse width=20us, duty cycle=10%, 5.8GHz)

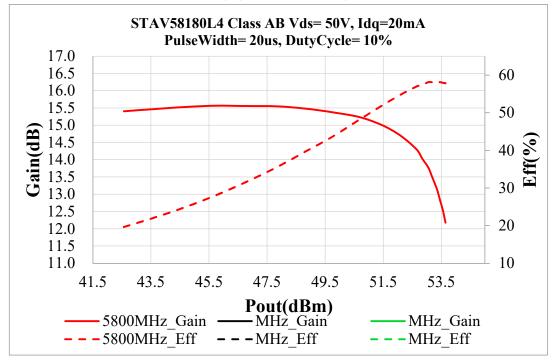
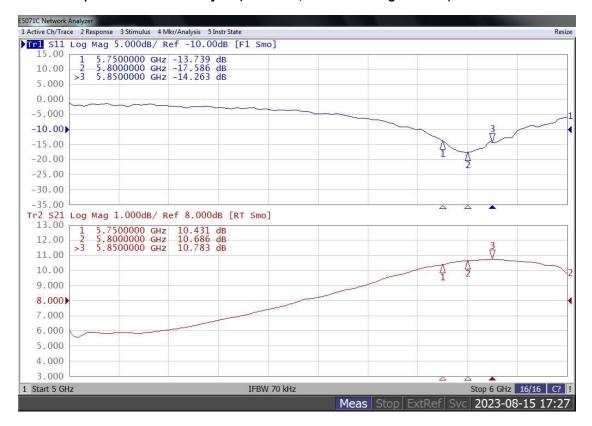
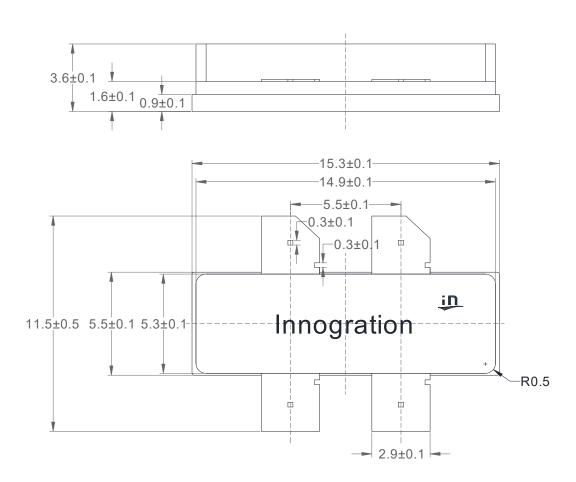


Figure 4: S11/S21 output from Network analyser (VDS= 50V, IDQ=100 mA Vgs =-3.08V)





## Earless Flanged Ceramic Package; 4 leads







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## **Revision history**

#### **Table 4. Document revision history**

Date	Revision	Datasheet Status
2023/8/15	V1.0	Preliminary Datasheet Creation

Application data based on: LSM-23-26

#### **Notice**

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